DM5401,DM7401

DM5401 DM7401 Quad 2-Input NAND Gates with Open-Collector Outputs

Literature Number: SNOS221A

National Semiconductor

June 1989

DM5401/DM7401 Quad 2-Input NAND Gates with Open-Collector Outputs

General Description

This device contains four independent gates each of which performs the logic NAND function. The open-collector outputs require external pull-up resistors for proper logical operation.

Pull-Up Resistor Equations

$$R_{MAX} = \frac{V_{CC}\,(Min) - V_{OH}}{N_1\,(I_{OH}) + N_2\,(I_{IH})}$$

$$R_{MIN} = \frac{V_{CC}\,(Max) - V_{OL}}{I_{OL} - N_3\,(I_{IL})}$$

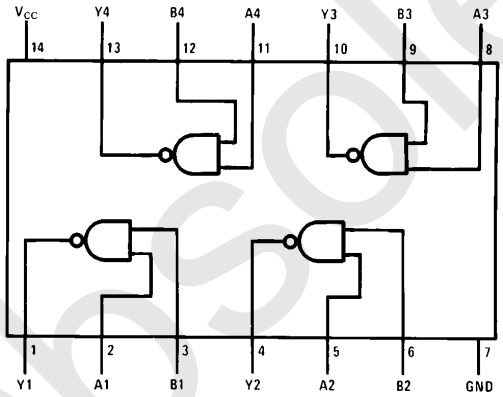
Where: $N_1\,(I_{OH})$ = total maximum output high current for all outputs tied to pull-up resistor

$N_2\,(I_{IH})$ = total maximum input high current for all inputs tied to pull-up resistor

$N_3\,(I_{IL})$ = total maximum input low current for all inputs tied to pull-up resistor

Connection Diagram

Dual-In-Line Package



TL/F/6614–1

Order Number DM5401J, DM5401W or DM7401N
See NS Package Number J14A, N14A or W14B

Function Table

$$Y = \overline{AB}$$

Inputs		Output
A	B	Y
L	L	H
L	H	H
H	L	H
H	H	L

H = High Logic Level

L = Low Logic Level

RRD-B30M105/Printed in U. S. A.

Absolute Maximum Ratings (Note)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage	7V
Input Voltage	5.5V
Output Voltage	7V
Operating Free Air Temperature Range	
DM54	−55°C to +125°C
DM74	0°C to +70°C
Storage Temperature Range	−65°C to +150°C

Note: *The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the "Electrical Characteristics" table are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.*

Recommended Operating Conditions

Symbol	Parameter	DM5401			DM7401			Units
		Min	Nom	Max	Min	Nom	Max	
V_{CC}	Supply Voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High Level Input Voltage	2			2			V
V_{IL}	Low Level Input Voltage			0.8			0.8	V
V_{OH}	High Level Output Voltage			5.5			5.5	V
I_{OL}	Low Level Output Current			16			16	mA
T_A	Free Air Operating Temperature	−55		125	0		70	°C

Electrical Characteristics over recommended operating free air temperature range (unless otherwise noted)

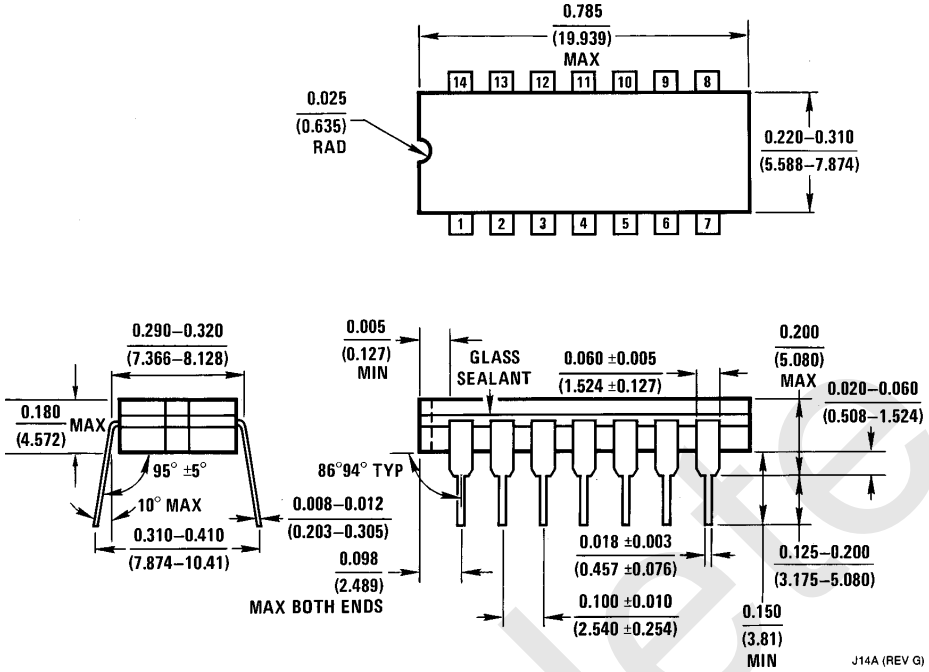
Symbol	Parameter	Conditions	Min	Typ (Note 1)	Max	Units
V_I	Input Clamp Voltage	V_{CC} = Min, I_I = −12 mA			−1.5	V
I_{CEX}	High Level Output Current	V_{CC} = Min, V_O = 5.5V V_{IL} = Max			250	μA
V_{OL}	Low Level Output Voltage	V_{CC} = Min, I_{OL} = Max V_{IH} = Min		0.2	0.4	V
I_I	Input Current @ Max Input Voltage	V_{CC} = Max, V_I = 5.5V			1	mA
I_{IH}	High Level Input Current	V_{CC} = Max, V_I = 2.4V			40	μA
I_{IL}	Low Level Input Current	V_{CC} = Max, V_I = 0.4V			−1.6	mA
I_{CCH}	Supply Current with Outputs High	V_{CC} = Max		4	8	mA
I_{CCL}	Supply Current with Outputs Low	V_{CC} = Max		12	22	mA

Switching Characteristics at V_{CC} = 5V and T_A = 25°C (See Section 1 for Test Waveforms and Output Load)

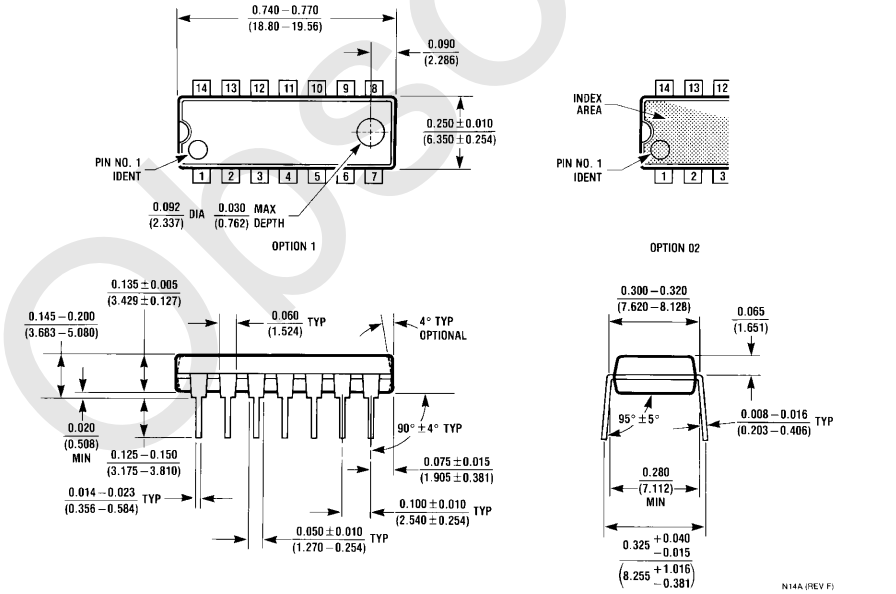
Symbol	Parameter	Conditions	Min	Max	Units
t_{PLH}	Propagation Delay Time Low to High Level Output	C_L = 15 pF R_L = 4 kΩ (t_{PLH}) R_L = 400Ω (t_{PHL})		45	ns
t_{PHL}	Propagation Delay Time High to Low Level Output			15	ns

Note 1: All typicals are at V_{CC} = 5V, T_A = 25°C.

Physical Dimensions inches (millimeters)

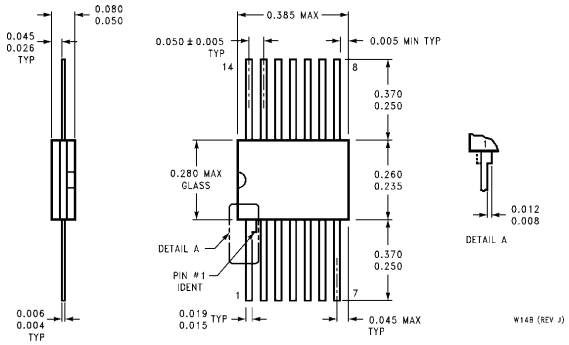


14-Lead Ceramic Dual-In-Line Package (J)
Order Number DM5401J
NS Package Number J14A



14-Lead Molded Dual-In-Line Package (N)
Order Number DM7401N
NS Package Number N14A

Physical Dimensions inches (millimeters) (Continued)



14-Lead Ceramic Flat Package (W)
Order Number DM5401W
NS Package Number W14B

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